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| Title of Change: | Large Scaled Integrated Circuits (LSI) FLIP Fab site transfer from ON Semiconductor Gunma, Japan to ON Semiconductor Niigata, Japan. | | | |
| Proposed first ship date: | 5 June 2017 | | | |
| Contact information: | Contact your local ON Semiconductor Sales Office or <Akira.Yoneyama@onsemi.com> | | | |
| Samples: | Contact your local ON Semiconductor Sales Office or <Akira.Yoneyama@onsemi.com> | | | |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com> | | | |
| Type of notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>. | | | |
| Change Part Identification: | Product lots will be identified through a data code on the parts. | | | |
| Change category: | <input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____ | | | |
| Change Sub-Category(s): | <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____ | | | |
| Sites Affected: | <input type="checkbox"/> All site(s) <input checked="" type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s) | | | |
| Description and Purpose: | To be able to continuously supply products and increase our supply capacity to support increased demand, LSI FLIP fab site will be transfer from ON Semiconductor Gunma, Japan to ON Semiconductor Niigata, Japan. All equipment and most personnel will be transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified. | | | |
| Reliability Data Summary: | Package: WLFCP-6 | | | |
| Test | Specification | Condition | Interval | Results |
| HTOL | JESD22-A108 | Ta=125°C, 100 % max rated Vcc | 1008 hrs | 0/231 |
| HTSL | JESD22-A103 | Ta= 150°C | 1008 hrs | 0/231 |
| TC | JESD22-A104 | Ta= -40°C to +125°C | 500 cyc | 0/231 |
| THB | JESD22-A101 | 85°C, 85% RH, max rated Vcc | 1008 hrs | 0/231 |
| Electrical Characteristic Summary: | Electrical characteristics are not impacted. | | | |
| List of affected Standard Parts: | | | | |
| Part Number | Qualification Vehicle | | | |
| LE24163LBXA-SH | LE2416RLBXA-SH | | | |
| LE24162LBXA-SH | | | | |
| LE2416RLBXA-SH | | | | |